

## Adapters

### QFP176 - TET

Target CPU package: QFP176  
 Body size: 24 mm x 24 mm  
 Pitch: 0.5 mm  
 POD target layout: T\_QFP176

Can be used with:

- MPC5604B ActiveGT POD
- MPC564xB ActiveGT POD
- TMS470Pxx Standard ActivePRO POD

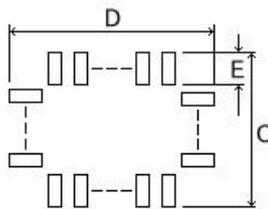
Note that adapter solutions stated in the document can be used only with listed PODs. Disregarding this warning may result in hardware failure of the target and the emulation system.

#### ► Available Adapter Parts (by ordering code):

- **IA176TQ-SOLDER**

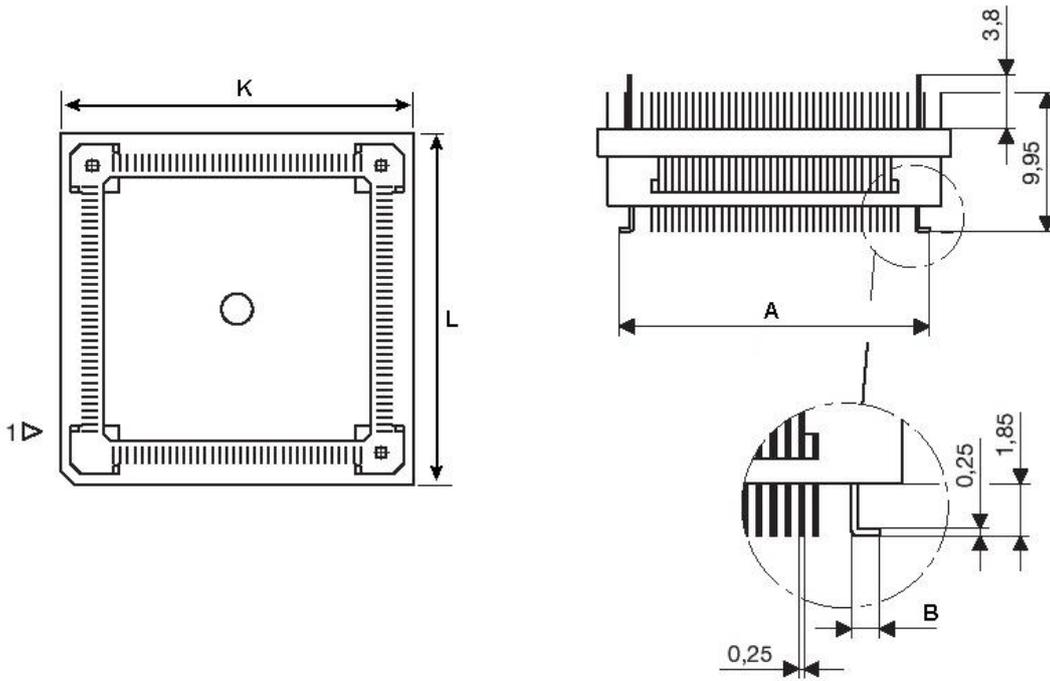


Solder part, which is being soldered to the target.



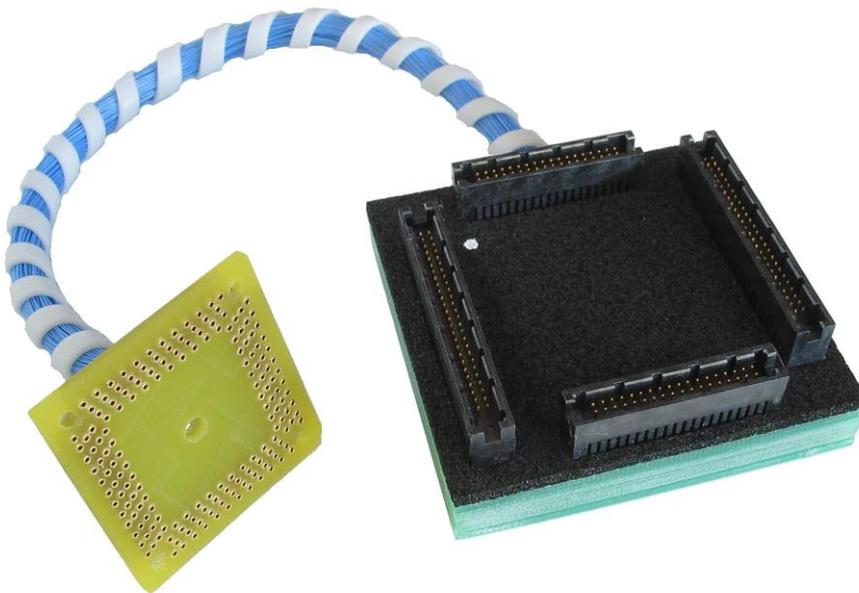
(Unit: mm)						
A	B	C	D	E	K	L
26.0	1.125	27.0	27.0	1.9	29.05	29.05

Recommended (by TET) PCB footprint size



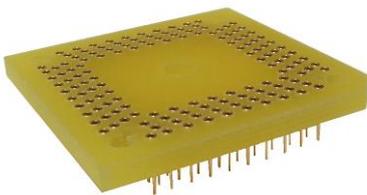
IA176TQ-SOLDER dimensions

- **IA176TQ-WIRE**



The IA176TQ-WIRE represents flexible connection between the POD and the target.

- **IA176TQEXT**



The IA176TQEXT is a 3 mm extension, which can be used as a “socket saver” to protect the more expensive IA176TQ-SOLDER part which may be damaged due to the carelessness when connecting/disconnecting the POD from the IA176TQ-WIRE part.

## Flexible Adapter

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The IA176TQ-WIRE and the IA176TQ-SOLDER are essential parts required to adapt the POD to the target QFP176 package. First, the IA176TQ-SOLDER is soldered to the target and then the POD is connected via the IA176TQ-WIRE.

### ► Assembly

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Pay attention to pin 1 while assembling the adapter and connecting the POD to the target. Improper use of the adapter or even incorrect adapter used with your particular POD can damage the emulation system and the target.

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1. First, solder the IA176TQ-SOLDER to the target PCB.
2. Next, connect the IA176TQ-WIRE to the POD.
3. Finally, connect the POD via the IA176TQ-WIRE to the target.

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Precaution must be taken after the POD is connected to the target. Adapter parts may break due to the user carelessness.

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